### SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

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- Complementary Outputs
- Direct Overriding Load (Data) Inputs
- Gated Clock Inputs
- Parallel-to-Serial Data Conversion

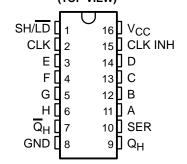
TYPE	TYPICAL MAXIMUM CLOCK FREQUENCY	TYPICAL POWER DISSIPATION
'165	26 MHz	210 mW
'LS165A	35 MHz	90 mW

#### description

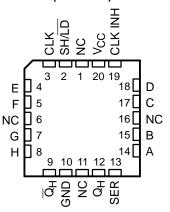
The '165 and 'LS165A are 8-bit serial shift registers that shift the data in the direction of  $Q_A$  toward  $Q_H$  when clocked. Parallel-in access to each stage is made available by eight individual, direct data inputs that are enabled by a low level at the shift/load (SH/ $\overline{LD}$ ) input. These registers also feature gated clock (CLK) inputs and complementary outputs from the eighth bit. All inputs are diode-clamped to minimize transmission-line effects, thereby simplifying system design.

Clocking is accomplished through a two-input positive-NOR gate, permitting one input to be used as a clock-inhibit function. Holding either of the clock inputs high inhibits clocking, and holding either clock input low with SH/LD high enables the other clock input. Clock inhibit (CLK INH) should be changed to the high level only while CLK is high. Parallel loading is inhibited as long as SH/LD is high. Data at the parallel inputs are loaded directly into the register while SH/LD is low, independently of the levels of CLK, CLK INH, or serial (SER) inputs.

SN54165, SN54LS165A . . . J OR W PACKAGE SN74165 . . . N PACKAGE SN74LS165A . . . D, N, OR NS PACKAGE (TOP VIEW)



# SN54LS165A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



The SN54165 and SN74165 devices are obsolete and are no longer supplied.

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#### **ORDERING INFORMATION**

TA	PAC	KAGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74LS165AN	SN74LS165AN
0°C to 70°C	SOIC - D	Tube	SN74LS165AD	LS165A
0°C to 70°C	30IC - D	Tape and reel	SN74LS165ADR	L3103A
	SOP - NS	Tape and reel	SN74LS165ANSR	74LS165A
	CDIP – J	Tube	SN54LS165AJ	SN54LS165AJ
EE°C to 125°C	CDIF - J	Tube	SNJ54LS165AJ	SNJ54LS165AJ
–55°C to 125°C	CFP – W	Tube	SNJ54LS165AW	SNJ54LS165AW
	LCCC - FK	Tube	SNJ54LS165AFK	SNJ54LS165AFK

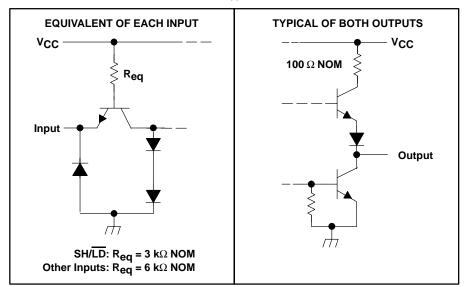
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

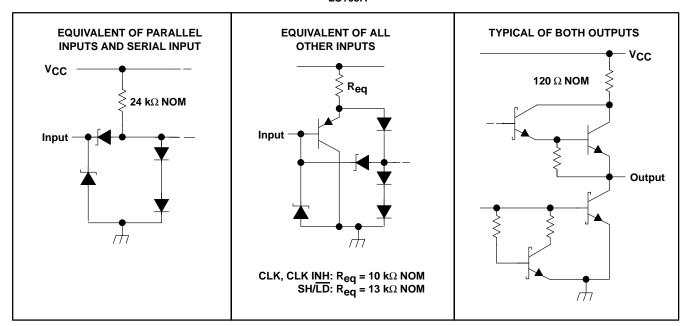
		INPUTS	5		l	RNAL PUTS	OUTPUT
SH/LD	CLK INH	CLK	SER	PARALLEL AH	$\overline{Q}_A$	$\overline{Q}_B$	QH
L	Х	Χ	Χ	ah	а	b	h
Н	L	L	Χ	Х	Q <sub>A0</sub>	$Q_{B0}$	Q <sub>H0</sub>
Н	L	$\uparrow$	Н	Х	Н	$Q_{An}$	$Q_{Gn}$
Н	L	$\uparrow$	L	Х	L	$Q_{An}$	$Q_{Gn}$
Н	Н	Χ	Χ	Х	Q <sub>A0</sub>	Q <sub>B0</sub>	Q <sub>H0</sub>

### schematics of inputs and outputs

'165

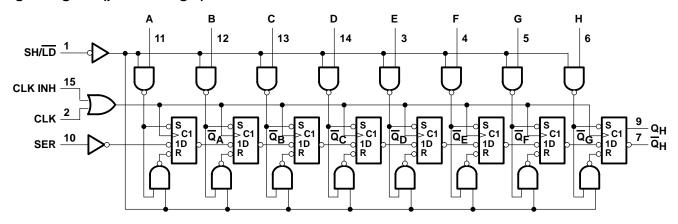


#### 'LS165A



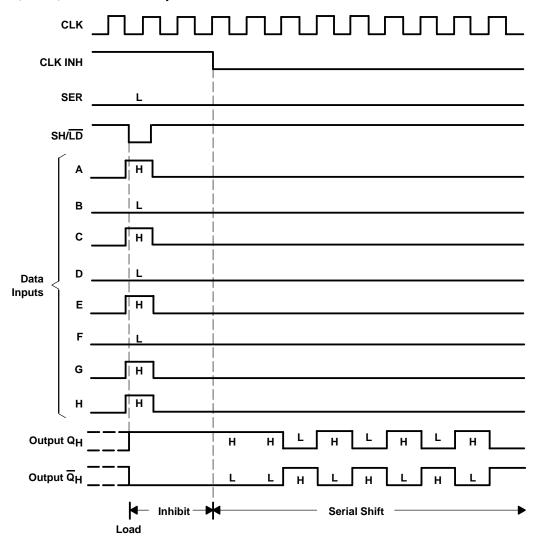
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### logic diagram (positive logic)



Pin numbers shown are for D, J, N, NS, and W packages.

### typical shift, load, and inhibit sequences



### SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

The SN54165 and SN74165 devices are obsolete and are no longer supplied.

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#### absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V <sub>CC</sub> (see Note 1)		7 V
Input voltage, V <sub>I</sub> : SN54165, SN74165		5.5 V
SN54LS165A, SN74LS165	5A	7 V
Interemitter voltage (see Note 2)		5.5 V
Package thermal impedance θ <sub>JA</sub> (see Note 3	): D package	73°C/W
	N package	67°C/W
	NS package	64°C/W
Storage temperature range, T <sub>sto</sub>		65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values, except interemitter voltage, are with respect to network ground terminal.
  - 2. This is the voltage between two emitters of a multiple-emitter transistor. This rating applies for the '165 to the SH/LD input in conjunction with the CLK INH input.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions

		,	SN54165		5	N74165		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
loн	High-level output current			-800			-800	μΑ
loL	Low-level output current			16			16	mA
fclock	Clock frequency	0		20	0		20	MHz
tw(clock)	Width of clock input pulse	25			25			ns
tw(load)	Width of load input pulse	15			15			ns
t <sub>su</sub>	Clock-enable setup time (see Figure 1)	30			30			ns
t <sub>su</sub>	Parallel input setup time (see Figure 1)	10			10			ns
t <sub>su</sub>	Serial input setup time (see Figure 1)	20			20			ns
t <sub>su</sub>	Shift setup time (see Figure 1)	45			45			ns
t <sub>h</sub>	Hold time at any input	0			0			ns
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	242445752			t	;	SN54165	1	;	SN74165	1	
	PARAMETER		TEST CO	NDITIONS†	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage				2			2			V
VIL	Low-level input voltage						0.8			0.8	V
VIK	Input clamp voltage		$V_{CC} = MIN,$	I <sub>I</sub> = -12 mA			-1.5			-1.5	V
Vон	High-level output voltage	output voltage		$V_{IH} = 2 \text{ V},$ $I_{OH} = -800 \mu\text{A}$	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	Low-level output voltage		V <sub>IH</sub> = 2 V, I <sub>OL</sub> = 16 mA		0.2	0.4		0.2	0.4	٧
II	Input current at maximum	n input voltage	$V_{CC} = MAX$ ,	V <sub>I</sub> = 5.5 V			1			1	mA
	High lovel input current	SH/LD	Vac - MAY	V: - 2.4 V			80			80	
l IH	High-level input current	Other inputs	$V_{CC} = MAX,$	V  = 2.4 V			40			40	μΑ
1	SH/LD		\/ MAY	V: - 0.4 V			-3.2			-3.2	mA
¹IL	Low-level input current Other inputs		$V_{CC} = MAX,$	V  = 0.4 V			-1.6			-1.6	IIIA
los	Short-circuit output current§		$V_{CC} = MAX$		-20		-55	-18		-55	mA
ICC	Supply current		$V_{CC} = MAX$ ,	See Note 4		42	63		42	63	mA

NOTE 4: With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD, I<sub>CC</sub> is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.

### SN54165 and SN74165 switching characteristics, $V_{CC} = 5 \text{ V}$ , $T_A = 25^{\circ}\text{C}$ (see Figure 1)

PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				20	26		MHz
<sup>t</sup> PLH	<u>ID</u>	Any	$C_L = 15 pF, R_L = 400 Ω$		21	31	ns
<sup>t</sup> PHL	LD	Arry	C <sub>L</sub> = 13 pr, κ <sub>L</sub> = 400 s <sub>2</sub>		27	40	115
<sup>t</sup> PLH	CLK	Any	$C_L = 15 \text{ pF, } R_L = 400 \Omega$		16	24	ns
<sup>t</sup> PHL	OLK	Ally	OL = 13 pr , 11 = 400 sz		21	31	115
<sup>t</sup> PLH	Н	0	$C_L$ = 15 pF, $R_L$ = 400 $\Omega$		11	17	ns
<sup>t</sup> PHL	11	Q <sub>H</sub>	C <sub>L</sub> = 13 pr, κ <sub>L</sub> = 400 s <sub>2</sub>		24	36	115
<sup>t</sup> PLH	Н	$\overline{\mathtt{Q}}_{H}$	C: - 15 pE P: - 400 O		18	27	no
<sup>t</sup> PHL	17	¥H L	$C_L = 15 \text{ pF}, R_L = 400 \Omega$		18	27	ns

<sup>¶</sup> f<sub>max</sub> = maximum clock frequency, t<sub>PLH</sub> = propagation delay time, low-to-high-level output, t<sub>PHL</sub> = propagation delay time, high-to-low-level output

<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

<sup>‡</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C.

<sup>§</sup> Not more than one output should be shorted at a time.

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#### recommended operating conditions

			SN	54LS16	5A	SN	74LS165	δA	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage		2			2			V
V <sub>IL</sub>	Low-level input voltage				0.7			0.8	V
IOH	High-level output current				-0.4			-0.4	mA
l <sub>OL</sub>	Low-level output current				4			8	mA
fclock	Clock frequency		0		25	0		25	MHz
	Width of clock input pulse (see Figure 2)	Clock high	15			15			ns
<sup>t</sup> w(clock)	whath of clock input pulse (see Figure 2)	Clock low	25			25			115
+ 4	Width of load input pulse	Clock high	25			25			ns
<sup>t</sup> w(load)	whath of load input pulse	Clock low	17			17			115
t <sub>su</sub>	Clock-enable setup time (see Figure 2)		30			30			ns
t <sub>su</sub>	Parallel input setup time (see Figure 2)		10			10			ns
t <sub>su</sub>	Serial input setup time (see Figure 2)		20			20			ns
t <sub>su</sub>	Shift setup time (see Figure 2)		45			45			ns
<sup>t</sup> h	Hold time at any input		0			0			ns
T <sub>A</sub>	Operating free-air temperature		-55	_	125	0		70	°C

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEOT	ONDITIONS		SN	I54LS16	5A	SN	74LS16	5A	
PARAMETER		1651 0		MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	$V_{CC} = MIN,$	$I_{I} = -18 \text{ mA}$					-1.5			-1.5	V
VOH	$V_{CC} = MIN,$	V <sub>IH</sub> = 2 V,	$V_{IL} = MAX$ ,	$I_{OH} = -0.4 \text{ mA}$	2.5	3.5		2.7	3.5		V
Voi	V <sub>CC</sub> = MIN,	\/ 2\/	\/ MAY	I <sub>OL</sub> = 4 mA		0.25	0.4		0.25	0.4	V
VOL	ACC = MINA	ν IH = 2 ν,	VIL = IVIAA	I <sub>OL</sub> = 8 mA					0.35	0.5	V
lį	$V_{CC} = MAX$ ,	V <sub>I</sub> = 7 V					0.1			0.1	mA
ΙΗ	$V_{CC} = MAX$ ,	V <sub>I</sub> = 2.7 V					20			20	μΑ
I₁∟	$V_{CC} = MAX$ ,	V <sub>I</sub> = 0.4 V					-0.4			-0.4	mA
I <sub>OS</sub> §	$V_{CC} = MAX$				-20		-100	-20		-100	mA
ICC	$V_{CC} = MAX$ ,	See Note 4				18	30		18	30	mA

NOTE 4. With the outputs open, CLK INH and CLK at 4.5 V, and a clock pulse applied to SH/LD, I<sub>CC</sub> is measured first with the parallel inputs at 4.5 V, then with the parallel inputs grounded.



<sup>†</sup> For conditions shown as MIN or MAX, use the appropriate values specified under recommended operating conditions.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

# SN54165, SN54LS165A, SN74165, SN74LS165A PARALLEL-LOAD 8-BIT SHIFT REGISTERS

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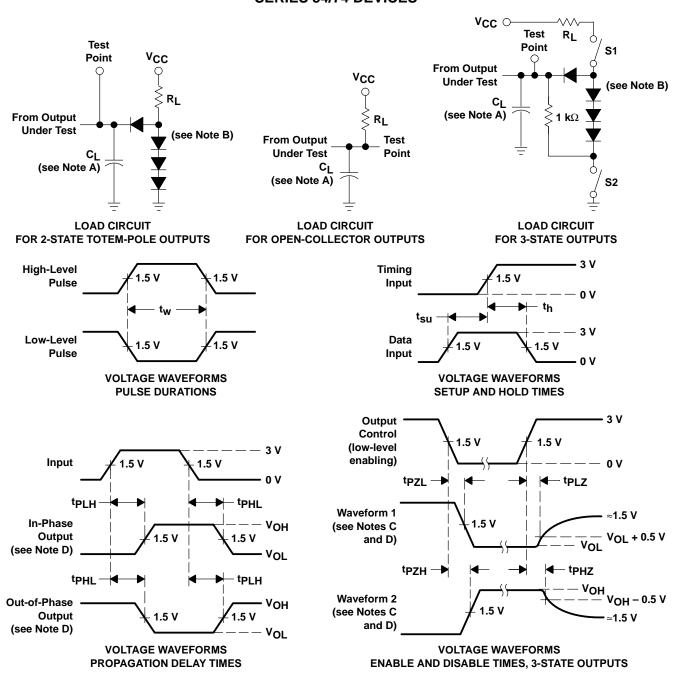
The SN54165 and SN74165 devices are obsolete and are no longer supplied.

# SN54LS165A and SN74LS165A switching characteristics, $V_{CC}$ = 5 V, $T_A$ = 25°C (see Figure 2)

PARAMETER†	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f <sub>max</sub>				25	35		MHz
t <sub>PLH</sub>	<u>LD</u>	Any	$R_L = 2 k\Omega$ , $C_L = 15 pF$		21	35	ns
t <sub>PHL</sub>	LD	Arry	N_ = 2 ks2, G_ = 15 pr		26	35	115
<sup>t</sup> PLH	CLK	Any	$R_L = 2 k\Omega$ , $C_L = 15 pF$		14	25	ns
t <sub>PHL</sub>	OLK	Arry	N_ = 2 ks2, G_ = 15 pr		16	25	115
<sup>t</sup> PLH	Н	0	$R_{\parallel} = 2 \text{ k}\Omega, C_{\parallel} = 15 \text{ pF}$		13	25	ns
<sup>t</sup> PHL	11	Q <sub>H</sub>	N <sub>L</sub> = 2 κ <sub>22</sub> , G <sub>L</sub> = 15 pr		24	30	115
<sup>t</sup> PLH	Н	<u></u>	D. 240 C. 45 pF		19	30	
t <sub>PHL</sub>	П	Q <sub>H</sub>	$R_L = 2 k\Omega$ , $C_L = 15 pF$		17	25	ns

<sup>†</sup> f<sub>max</sub> = maximum clock frequency, t<sub>PLH</sub> = propagation delay time, low-to-high-level output, t<sub>PHL</sub> = propagation delay time, high-to-low-level output

# PARAMETER MEASUREMENT INFORMATION SERIES 54/74 DEVICES

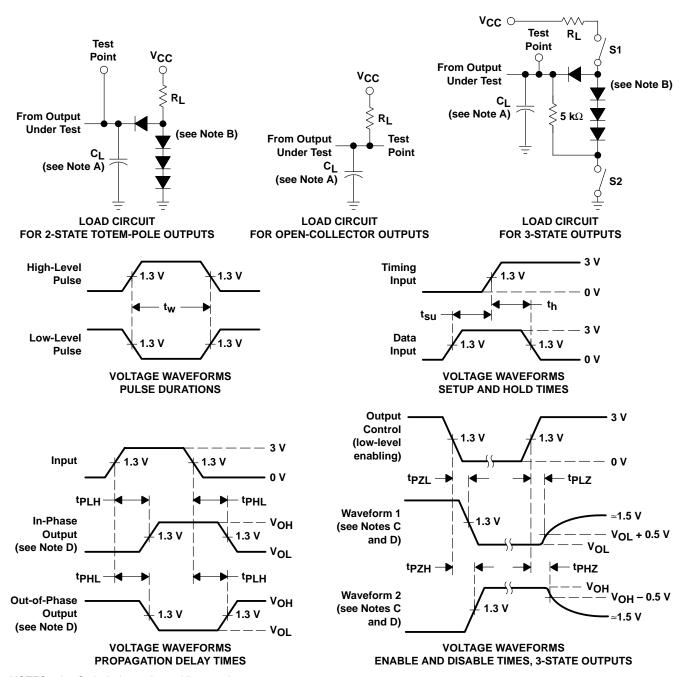


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. All diodes are 1N3064 or equivalent.
  - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - D. S1 and S2 are closed for tpLH, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
  - E. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O \approx 50 \Omega$ ;  $t_r$  and  $t_f \leq$  7 ns for Series 54/74 devices and  $t_r$  and  $t_f \leq$  2.5 ns for Series 54S/74S devices.
  - F. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



#### PARAMETER MEASUREMENT INFORMATION **SERIES 54LS/74LS DEVICES**



- NOTES: A. CL includes probe and jig capacitance.
  - B. All diodes are 1N3064 or equivalent.
  - C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - D. S1 and S2 are closed for tpLH, tpHL, tpHZ, and tpLZ; S1 is open and S2 is closed for tpZH; S1 is closed and S2 is open for tpZL.
  - E. Phase relationships between inputs and outputs have been chosen arbitrarily for these examples.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O \approx 50 \ \Omega$ ,  $t_r \leq 1.5 \ ns$ ,  $t_f \leq 2.6 \ ns$ .
  - The outputs are measured one at a time with one input transition per measurement.

Figure 2. Load Circuits and Voltage Waveforms



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### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-7700601VEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7700601VE A SNV54LS165AJ	Samples
5962-7700601VFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-7700601VF A SNV54LS165AW	Samples
7700601EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7700601EA SNJ54LS165AJ	Samples
7700601FA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7700601FA SNJ54LS165AW	Samples
JM38510/30608B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608B2A	Samples
JM38510/30608BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608BEA	Samples
JM38510/30608BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608BFA	Samples
M38510/30608B2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608B2A	Samples
M38510/30608BEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608BEA	Samples
M38510/30608BFA	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 30608BFA	Samples
SN54LS165AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54LS165AJ	Samples
SN74LS165AD	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165ADR	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LS165A	Samples
SN74LS165AN	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS165AN	Samples
SN74LS165ANE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74LS165AN	Samples
SN74LS165ANSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS165A	Samples

### PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS165AFK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54LS 165AFK	Samples
SNJ54LS165AJ	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7700601EA SNJ54LS165AJ	Samples
SNJ54LS165AW	ACTIVE	CFP	W	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	7700601FA SNJ54LS165AW	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### PACKAGE OPTION ADDENDUM

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#### OTHER QUALIFIED VERSIONS OF SN54LS165A, SN54LS165A-SP, SN74LS165A:

• Catalog : SN74LS165A, SN54LS165A

• Military : SN54LS165A

• Space : SN54LS165A-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

### **PACKAGE MATERIALS INFORMATION**

www.ti.com 9-Aug-2022

#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS165ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS165ANSR	so	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

# **PACKAGE MATERIALS INFORMATION**

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#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS165ADR	SOIC	D	16	2500	340.5	336.1	32.0
SN74LS165ANSR	so	NS	16	2000	367.0	367.0	38.0

# **PACKAGE MATERIALS INFORMATION**

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#### **TUBE**



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-7700601VFA	W	CFP	16	1	506.98	26.16	6220	NA
7700601FA	W	CFP	16	1	506.98	26.16	6220	NA
JM38510/30608B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
JM38510/30608BFA	W	CFP	16	1	506.98	26.16	6220	NA
M38510/30608B2A	FK	LCCC	20	1	506.98	12.06	2030	NA
M38510/30608BFA	W	CFP	16	1	506.98	26.16	6220	NA
SN74LS165AD	D	SOIC	16	40	507	8	3940	4.32
SN74LS165AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS165AN	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS165ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SN74LS165ANE4	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54LS165AFK	FK	LCCC	20	1	506.98	12.06	2030	NA
SNJ54LS165AW	W	CFP	16	1	506.98	26.16	6220	NA

# FK (S-CQCC-N\*\*)

### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# W (R-GDFP-F16)

### CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP2-F16



#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



#### NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



#### NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



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